

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHUN-WEN LAI	08/13/2019
JIEBIN FANG	08/13/2019
GANG CHEN	08/13/2019
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<b>Name:</b>	GUANDONG AIKO SOLAR ENERGY TECHNOLOGY CO., LTD.
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<b>Internal Address:</b>	SANSHUI DISTRICT
<b>City:</b>	FOSHAN, GUANGDONG
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	528000
<b>Name:</b>	ZHEJIANG AIKO SOLAR ENERGY TECHNOLOGY CO., LTD.
<b>Street Address:</b>	NO. 655, HAOPAI ROAD, SUXI TOWN
<b>City:</b>	YIWU CITY, ZHEJIANG PROVINCE
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<b>Postal Code:</b>	322009
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16490862
<b>CORRESPONDENCE DATA</b>	
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<b>NAME OF SUBMITTER:</b>	JIANPING ZHANG
<b>SIGNATURE:</b>	/Jianping Zhang/
<b>DATE SIGNED:</b>	09/20/2019
<b>Total Attachments: 3</b> source=assign dec 408USPC#page1.tif source=assign dec 408USPC#page2.tif source=assign dec 408USPC#page3.tif	

**COMBINED DECLARATION (37 CFR 1.63) FOR U.S. PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT OF INVENTION**

<b>Title of Invention</b>	PERC SOLAR CELL CAPABLE OF IMPROVING PHOTOELECTRIC CONVENRSION EFFICIENCY AND PREPARATION METHOD THEREOF
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**DECLARATION**

As the below named and undersigned inventor, I hereby declare that:

This declaration is directed to:

The attached application, or

United States application or PCT international application number PCT/CN2017/089884 filed on June 24, 2017

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Note to Inventor: 37 C.F.R. § 1.63(c) states: *A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56.*

**ASSIGNMENT**

WHEREAS, we,

Name	Address
Chun-Wen LAI	No.3, South Qili Avenue, Leping Town, Sanshui District, Foshan, Guangdong, 528000, China ;
Jiebin FANG	No.3, South Qili Avenue, Leping Town, Sanshui District, Foshan, Guangdong, 528000, China ;
Gang CHEN	No.3, South Qili Avenue, Leping Town, Sanshui District, Foshan, Guangdong, 528000, China ;

(hereinafter referred to as ASSIGNORS), having mailing addresses as listed above, are the joint inventors of an invention entitled "TBD," as described and claimed in the specification of International Application No. PCT/CN2017/089884, accorded an International Filing Date of June 24, 2017, for which an application for United States letters patent is sought;

*Seed Intellectual Property Law Group LLP*

WHEREAS,

Corporation Name	Address
Guangdong Aiko Solar Energy Technology Co., Ltd.	No.3, South Qili Avenue, Leping Town, Sanshui District, Foshan, Guangdong, 528000, China
Zhejiang Aiko Solar Energy Technology Co., Ltd.	No.655, Haopai Road, Suxi Town, Yiwu City, Zhejiang Province 322009, China

(hereinafter referred to as ASSIGNEE), having a usual place of business at the address listed above, is desirous of acquiring the entire right, title and interest in and to the invention in all countries throughout the world and in and to any letters patent that may be granted therefor in the United States;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have assigned and do hereby assign to the ASSIGNEE, and its lawful successors and assigns, the entire right, title, and interest in and to said invention, the above-identified United States patent application and all divisions, continuations, and continuations-in-part of said application, and reissues, extensions, and renewals of Letters Patent granted thereon, including the right to sue and collect damages for past and present infringement of said letters patent; and all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and all Letters Patents issuing on any such patent applications in the United States and foreign countries;

I hereby assign to the ASSIGNEE, and its lawful successors and assigns, the right to file patent applications in foreign countries on said invention in its own name and the right to claim priority to the above-identified United States patent application under the terms of the International Convention and any other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

*Seed Intellectual Property Law Group LLP*

IN TESTIMONY WHEREOF, I have hereunto set my hands.		
NAME OF INVENTOR (Full Legal Name) : <u>Chun-Wen LAI</u>		
Signature:	<u>賴俊文 Chun-Wen Lai</u>	Date: <u>2019.8.13</u>
NAME OF INVENTOR (Full Legal Name) : <u>Jiebin FANG</u>		
Signature:	<u>方结彬 Jiebin Fang</u>	Date: <u>2019.8.13</u>
NAME OF INVENTOR (Full Legal Name) : <u>Gang CHEN</u>		
Signature:	<u>陳剛 Gang Chen</u>	Date: <u>2019.8.13</u>

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*Seed Intellectual Property Law Group LLP*